



# Surface Mount Schottky Power Rectifier

## SMA/SMB Power Surface Mount Package

**MBRS2H100T3G,  
NBRS2H100T3G,  
NBRS2H100NT3G,  
MBRA2H100T3G,  
NRVBA2H100T3G,  
NRVBA2H100NT3G**

This device employs the Schottky Barrier principle in a metal-to-silicon power rectifier. Features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency switching power supplies; free wheeling diodes and polarity protection diodes.

### Features

- Compact Package with J-Bend Leads Ideal for Automated Handling
- Highly Stable Oxide Passivated Junction
- Guard-Ring for Overvoltage Protection
- Low Forward Voltage Drop
- NBR and NRVB Prefixes for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable\*

### Mechanical Characteristics

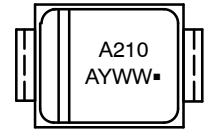
- Case: Molded Epoxy
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 70 mg (SMA), 95 mg (SMB) (Approximately)
- Cathode Polarity Band
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- ESD Ratings:
  - ◆ Charged Device Model > 1000 V (Class C5)
  - ◆ Human Body Model = 3B
- These Devices are Pb-Free and are RoHS Compliant
- Device Meets MSL1 Requirements

## SCHOTTKY BARRIER RECTIFIER 2.0 AMPERES, 100 VOLTS

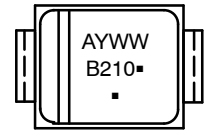
### MARKING DIAGRAMS



SMA  
CASE 403D



SMB  
CASE 403A



- A210 = MBRA2H100T3G  
NRVBA2H100T3G  
B210 = MBRS2H100T3G  
NBRS2H100T3G  
A = Assembly Location  
Y = Year  
WW = Work Week  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

\*\*The Assembly Location code (A) is front side optional. In cases where the Assembly Location is stamped in the package, the front side assembly code may be blank.

### ORDERING INFORMATION

Device	Package	Shipping†
MBRA2H100T3G, NRVBA2H100T3G*	SMA (Pb-Free)	5,000 / Tape & Reel
MBRS2H100T3G, NBRS2H100T3G* NBRS2H100NT3G*, NBRS2H100T3G-VF01*	SMB (Pb-Free)	2,500 / Tape & Reel
NRVBA2H100NT3G*	SMA (Pb-Free)	5,000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

**MBRS2H100T3G, NBRS2H100T3G, NBRS2H100NT3G, MBRA2H100T3G,  
NRVBA2H100T3G, NRVBA2H100NT3G**

**MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$V_{RRM}$ $V_{RWM}$ $V_R$	100	V
Average Rectified Forward Current ( $T_L = 150^\circ\text{C}$ )	$I_O$	2.0	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	$I_{FSM}$	130	A
Storage Temperature Range	$T_{stg}$	-65 to +175	$^\circ\text{C}$
Operating Junction Temperature (Note 1)	$T_J$	-65 to +175	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- The heat generated must be less than the thermal conductivity from Junction-to-Ambient:  $dP_D/dT_J < 1/R_{\theta JA}$ .

**THERMAL CHARACTERISTICS**

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Lead (Note 2) MBRA2H100T3G, NRVBA2H100T3G, NRVBA2H100NT3G MBRS2H100T3G, NBRS2H100T3G, NBRS2H100NT3G	$\Psi_{JCL}$	14 12	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient (Note 2) MBRA2H100T3G, NRVBA2H100T3G, NRVBA2H100NT3G MBRS2H100T3G, NBRS2H100T3G, NBRS2H100NT3G	$R_{\theta JA}$	75 71	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient (Note 3) MBRA2H100T3G, NRVBA2H100T3G, NRVBA2H100NT3G MBRS2H100T3G, NBRS2H100T3G, NBRS2H100NT3G	$R_{\theta JA}$	275 230	$^\circ\text{C}/\text{W}$

- Mounted with 700 mm square copper pad size (Approximately 1 inch square) 1 oz FR4 Board.
- Mounted with minimum recommended pad size 1 oz FR4 Board.

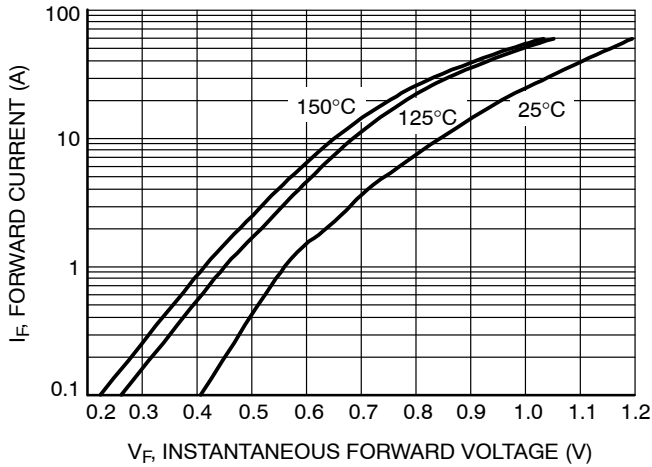
**ELECTRICAL CHARACTERISTICS**

Characteristic	Symbol	Value		Unit
		$T_J = 25^\circ\text{C}$	$T_J = 125^\circ\text{C}$	
Maximum Instantaneous Forward Voltage (Note 4) ( $I_F = 2.0 \text{ A}$ )	$V_F$	0.79	0.65	V
Maximum Instantaneous Reverse Current (Note 4) ( $V_R = 100 \text{ V}$ )	$I_R$	0.008	1.5	mA

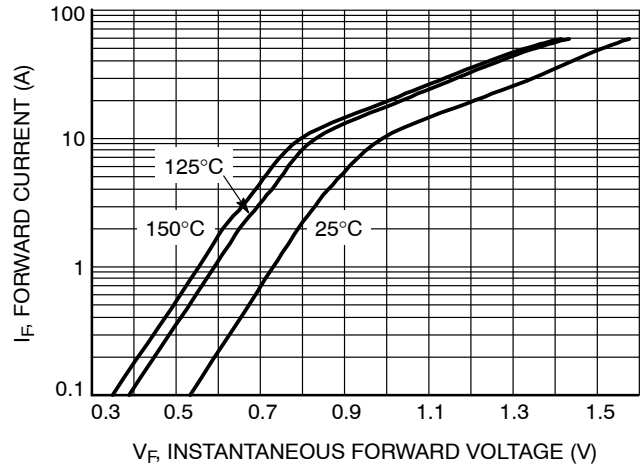
- Pulse Test: Pulse Width  $\leq 380 \mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ .

**MBRS2H100T3G, NBRS2H100T3G, NBRS2H100NT3G, MBRA2H100T3G,  
NRVBA2H100T3G, NRVBA2H100NT3G**

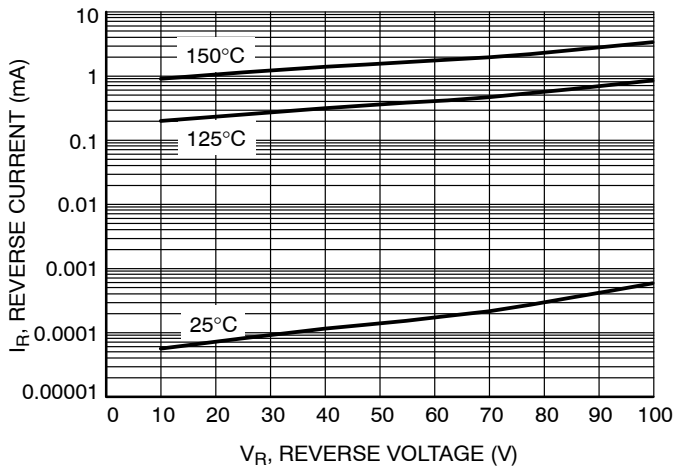
**TYPICAL CHARACTERISTICS**



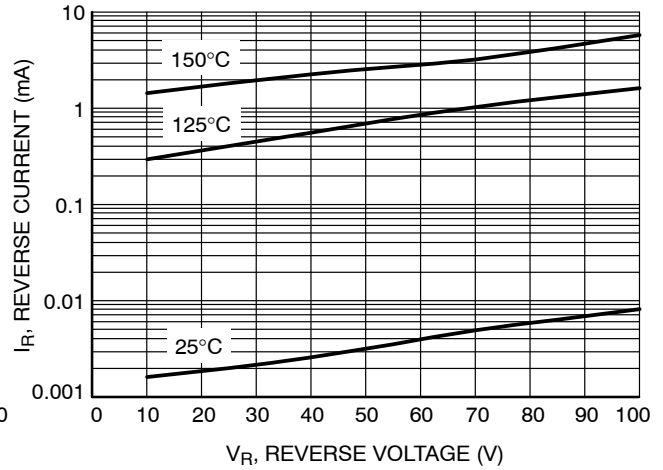
**Figure 1. Typical Forward Voltage**



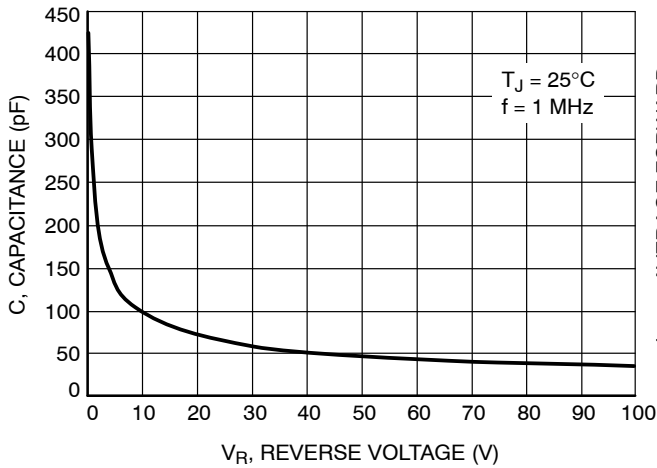
**Figure 2. Maximum Forward Voltage**



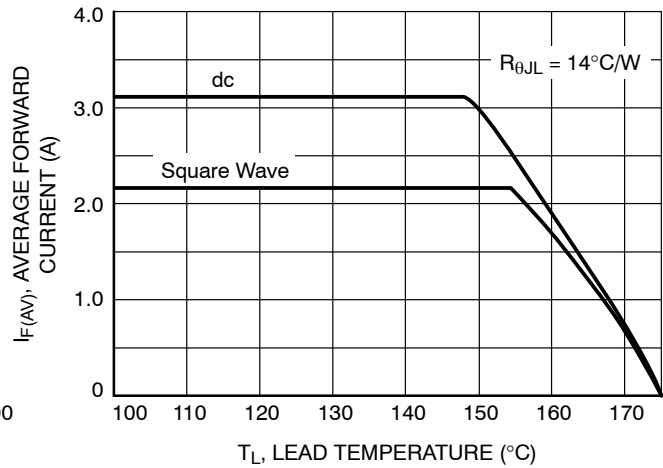
**Figure 3. Typical Reverse Current**



**Figure 4. Maximum Reverse Current**

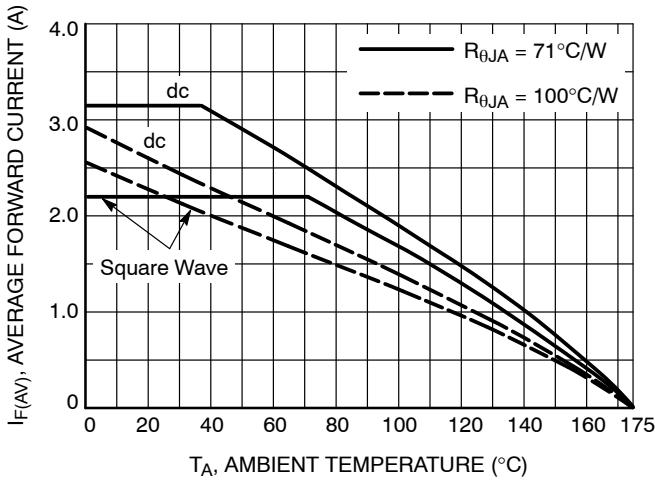


**Figure 5. Typical Capacitance**

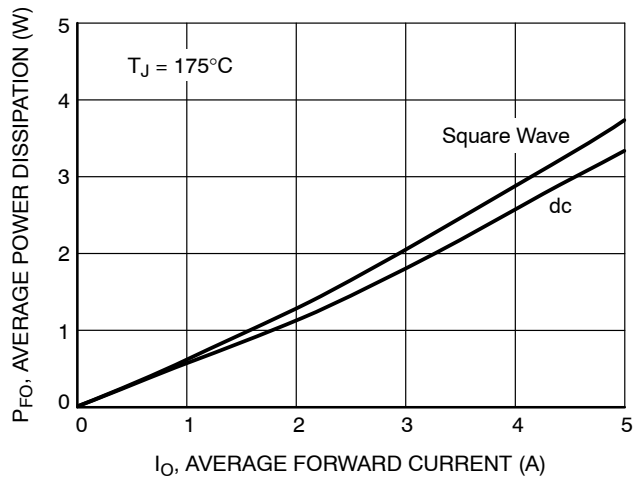


**Figure 6. Current Derating - Lead**

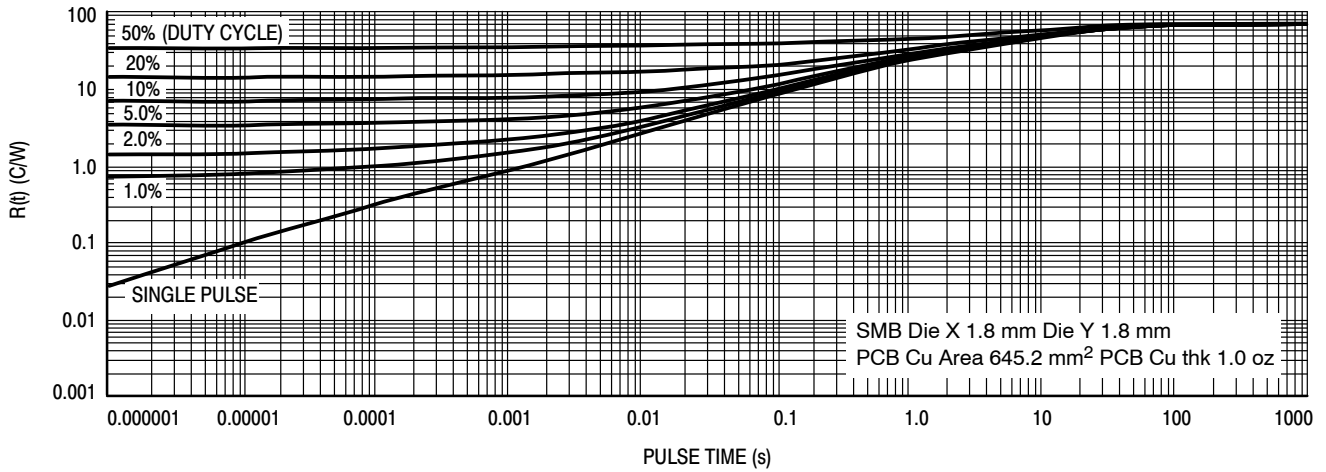
**MBRS2H100T3G, NBR2H100T3G, NBR2H100NT3G, MBRA2H100T3G,  
NRVBA2H100T3G, NRVBA2H100NT3G**  
**TYPICAL CHARACTERISTICS**



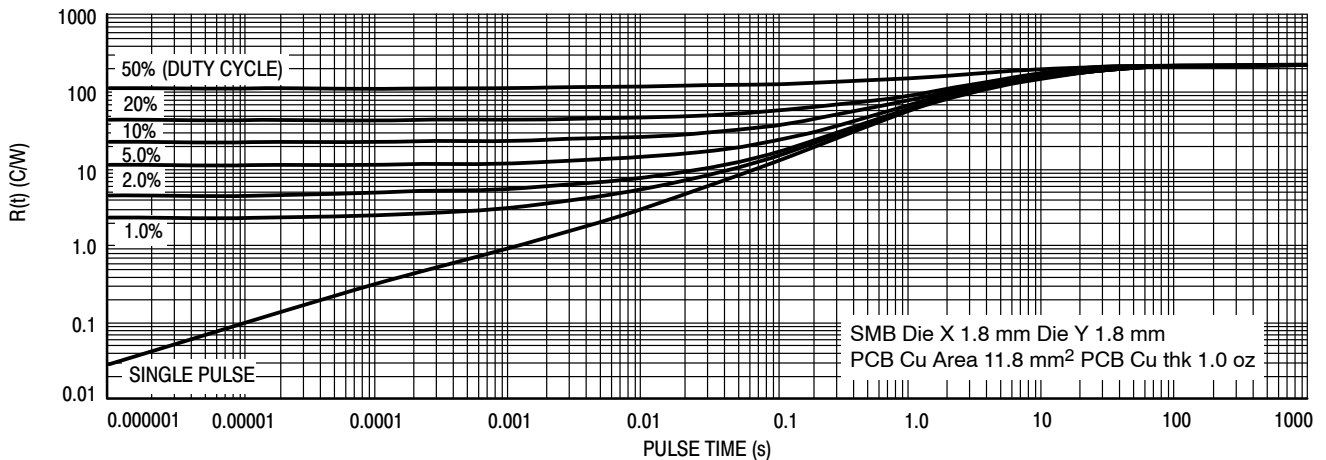
**Figure 7. Current Derating, Ambient**



**Figure 8. Maximum Forward Power Dissipation**

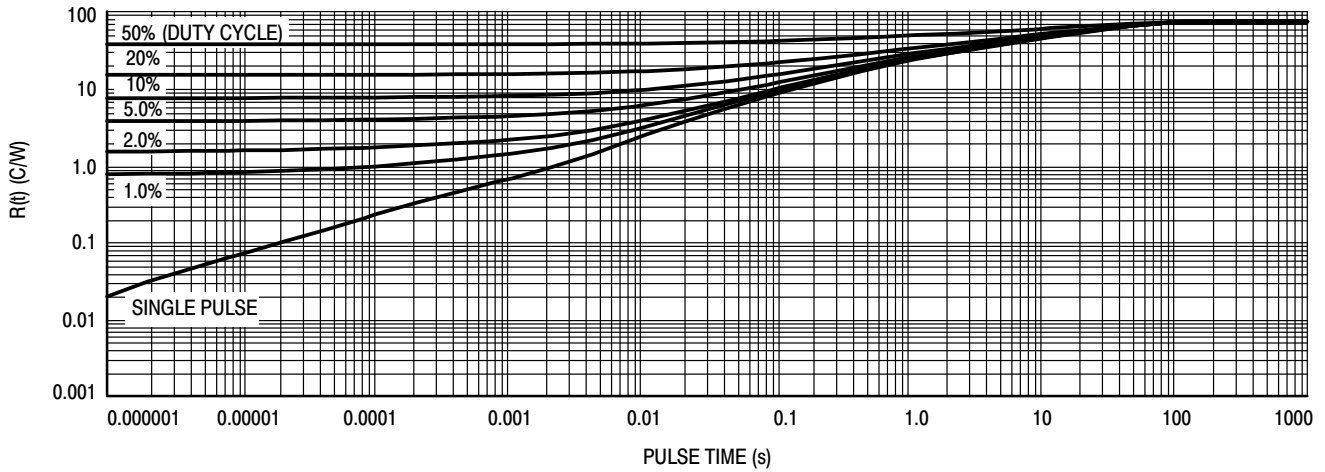


**Figure 9. Thermal Response, Junction-to-Ambient (1 inch pad) –  
MBRS2H100T3G/NBR2H100T3G/NBR2H100NT3G**

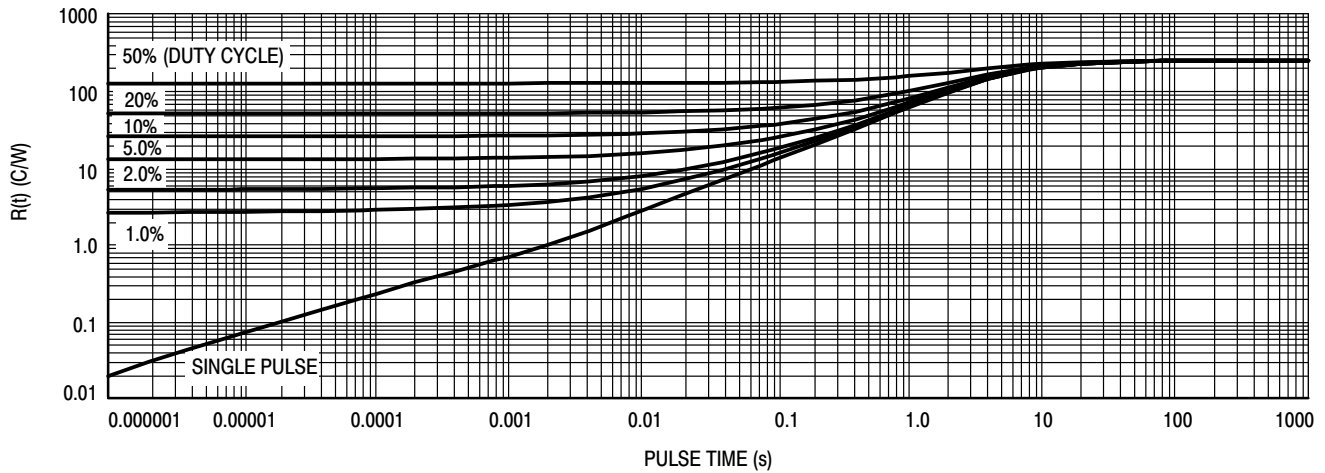


**Figure 10. Thermal Response, Junction-to-Ambient (min pad) –  
MBRS2H100T3G/NBR2H100T3G/NBR2H100NT3G**

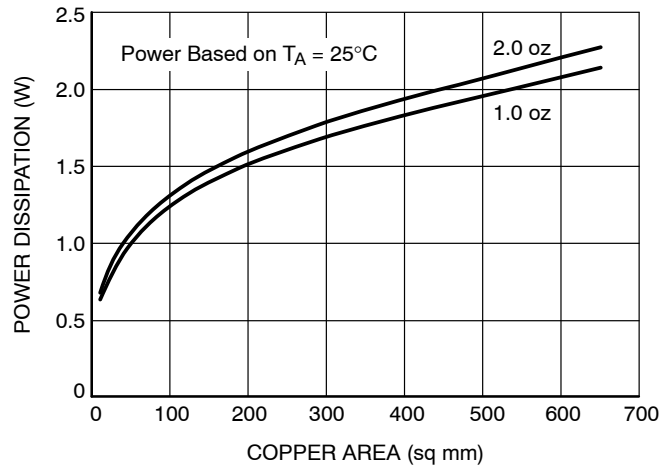
**MBRS2H100T3G, NBR2H100T3G, NBR2H100NT3G, MBRA2H100T3G,  
NRVBA2H100T3G, NRVBA2H100NT3G  
TYPICAL CHARACTERISTICS**



**Figure 11. Thermal Response, Junction-to-Ambient (1 inch pad) – MBRA2H100T3G/NRVBA2H100T3G**



**Figure 12. Thermal Response, Junction-to-Ambient (min pad) – MBRA2H100T3G/NRVBA2H100T3G**



**Figure 13.  $P_D$ , Junction-to-Ambient (URS copper area)**

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

ON Semiconductor®



SCALE 1:1

Polarity Band

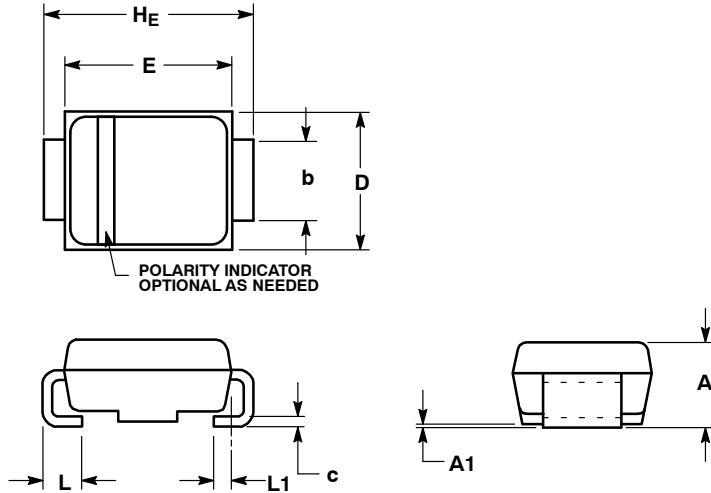


SCALE 1:1

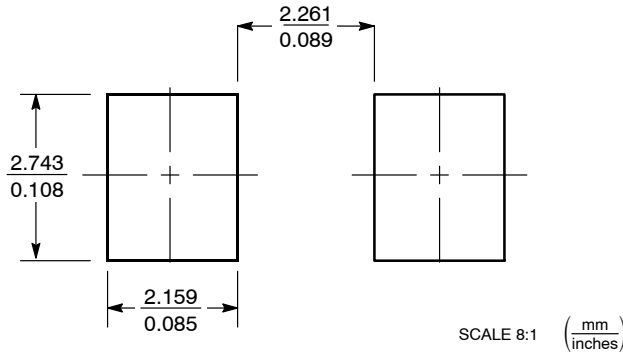
Non-Polarity Band

**SMB**  
CASE 403A-03  
ISSUE J

DATE 19 JUL 2012



**SOLDERING FOOTPRINT\***



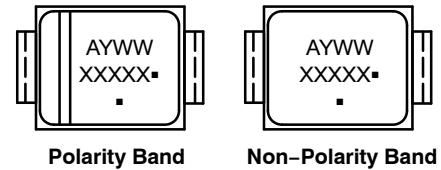
\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION b SHALL BE MEASURED WITHIN DIMENSION L1.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.95	2.30	2.47	0.077	0.091	0.097
A1	0.05	0.10	0.20	0.002	0.004	0.008
b	1.96	2.03	2.20	0.077	0.080	0.087
c	0.15	0.23	0.31	0.006	0.009	0.012
D	3.30	3.56	3.95	0.130	0.140	0.156
E	4.06	4.32	4.60	0.160	0.170	0.181
HE	5.21	5.44	5.60	0.205	0.214	0.220
L	0.76	1.02	1.60	0.030	0.040	0.063
L1	0.51 REF			0.020 REF		

**GENERIC MARKING DIAGRAM\***



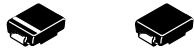
- XXXXX = Specific Device Code
  - A = Assembly Location
  - Y = Year
  - WW = Work Week
  - = Pb-Free Package
- (Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

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# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

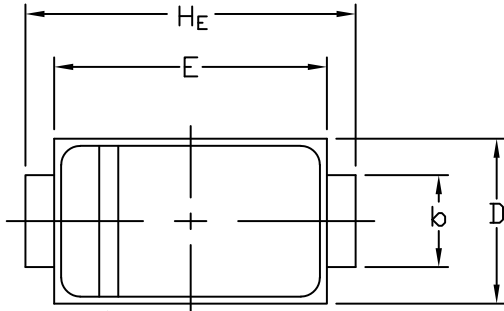


STYLE 1    STYLE 2

SCALE 1:1

**SMA**  
CASE 403D  
ISSUE J

DATE 22 OCT 2021

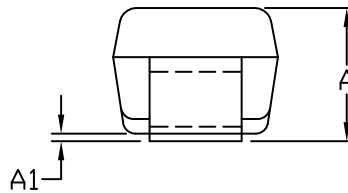
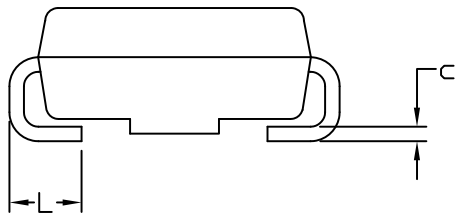


POLARITY INDICATOR  
OPTIONAL AS NEEDED

NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCHES
3. DIMENSION *b* SHALL BE MEASURED WITHIN DIMENSION L.

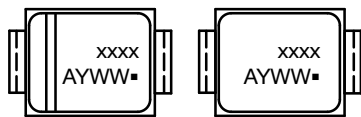
DIM	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	1.97	2.10	2.20	0.078	0.083	0.087
A1	0.05	0.10	0.20	0.002	0.004	0.008
<i>b</i>	1.27	1.45	1.63	0.050	0.057	0.064
<i>c</i>	0.15	0.28	0.41	0.006	0.011	0.016
D	2.29	2.60	2.92	0.090	0.103	0.115
E	4.06	4.32	4.57	0.160	0.170	0.180
HE	4.83	5.21	5.59	0.190	0.205	0.220
L	0.76	1.14	1.52	0.030	0.045	0.060



STYLE 1:  
PIN 1. CATHODE (POLARITY BAND)  
2. ANODE

STYLE 2:  
NO POLARITY

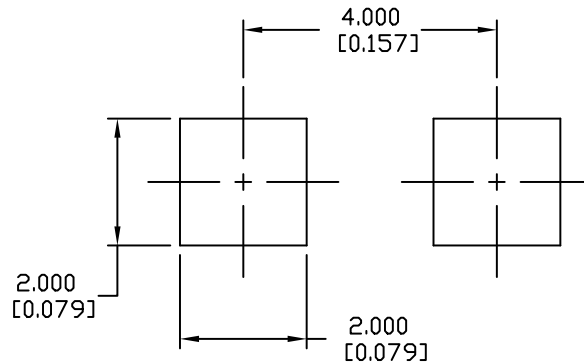
**GENERIC  
MARKING DIAGRAM\***



STYLE 1                      STYLE 2

- xxxx = Specific Device Code
- A = Assembly Location
- Y = Year
- WW = Work Week
- = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.



RECOMMENDED  
MOUNTING FOOTPRINT

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-  Cost Control Management
-  Shortage Management
-  Alternative Solution
-  Excess Inventory Management